

Product Summary

V _{(BR)DSS}	R _{DS(on)MAX}	I D
60)/	190mΩ@-10V	1.64
-60V	250mΩ@-4.5V	-1.6A

Feature

- Advanced trench process technology
- High density cell design for ultra low on-resistance

Application

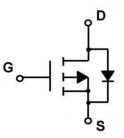
- Load Switch for Portable Devices
- DC/DC Converter

Package

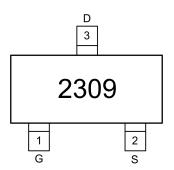


SOT-23

Circuit diagram



Marking





Absolute maximum ratings (Ta=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I _D	-1.6	Α
Pulsed Drain Current	I _{DM}	-8	А
Power Dissipation	P _D	1.5	W
Junction Temperature	TJ	150	$^{\circ}\mathbb{C}$
Storage Temperature	T _{STG}	-55 ~ +150	$^{\circ}\mathbb{C}$

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Static Characteristics	•		•	•			
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	-60			V	
Zero gate voltage drain current	I _{DSS}	V _{DS} =-60V,V _{GS} = 0V			-1	μA	
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA	
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	-1.4		-2.5	V	
Drain-source on-resistance ¹⁾		V _{GS} =-10V, I _D =-1.5A			190	10	
	R _{DS(on)}	V _{GS} =-4.5V, I _D =-1.0A			250	mΩ	
Dynamic characteristics ²⁾	1		•	•			
Input Capacitance	Ciss			370		pF	
Output Capacitance	Coss	V _{DS} =-30V,V _{GS} =0V,f =1MHz		32			
Reverse Transfer Capacitance	Crss			5			
Total Gate Charge	Qg			14.5		nC	
Gate-Source Charge	Qgs	Vps =-30V,Vgs =-10V, Ip =-1.5A		2.3			
Gate-Drain Charge	Qgd	- ID 1.5A		3.3			
Turn-on delay time	t _{d(on)}			40			
Turn-on rise time	tr	V_{DD} =-30V, V_{GS} =-10V, R_{GEN} =3 Ω		35		nS	
Turn-off delay time	t _{d(off)}			15			
Turn-off fall time	tf			10			
Source-Drain Diode characteristi	cs			•			
Diode Forward Current ¹⁾	Is				-1.6	Α	
Diode Forward voltage	V _{DS}	V _{GS} =0V, I _S =-1.5A			-1.2	V	

Notes: (1) Pulse Test: Pulse Width < 300µs, Duty Cycle ≤2%. (2) Guaranteed by design, not subject to production testing.



Typical Characteristics

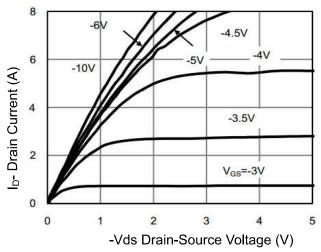


Figure 1 Output Characteristics

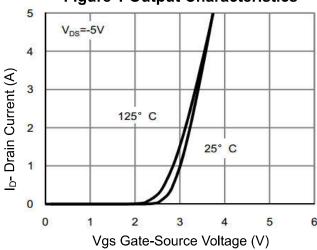


Figure 2 Transfer Characteristics

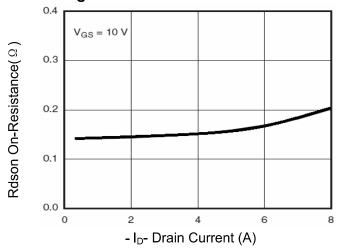


Figure 3 Rdson- Drain Current

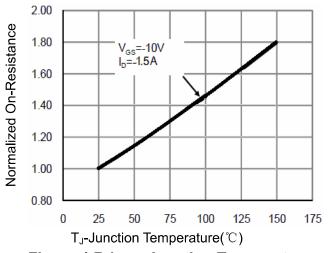


Figure 4 Rdson-Junction Temperature

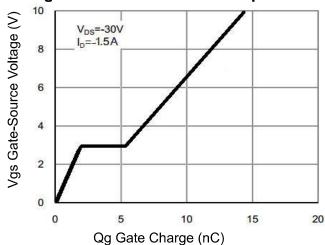


Figure 5 Gate Charge

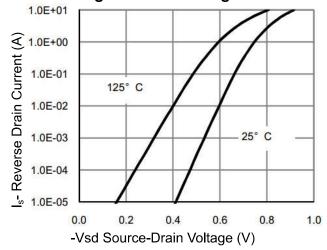


Figure 6 Source- Drain Diode Forward

Typical Characteristics

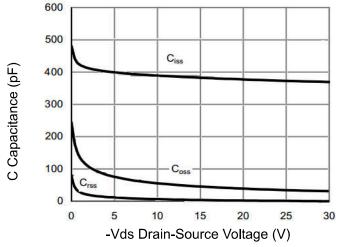


Figure 7 Capacitance vs Vds

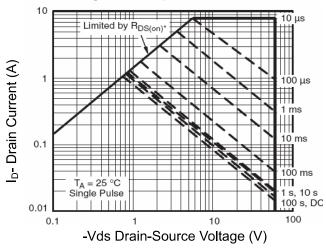
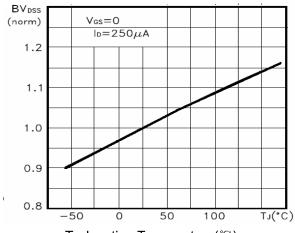


Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)

Figure 9 BV_{DSS} vs Junction Temperature

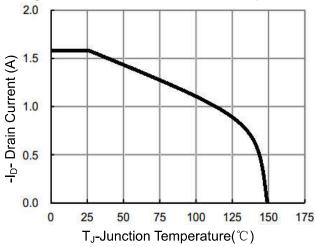


Figure 10 ID Current De-rating

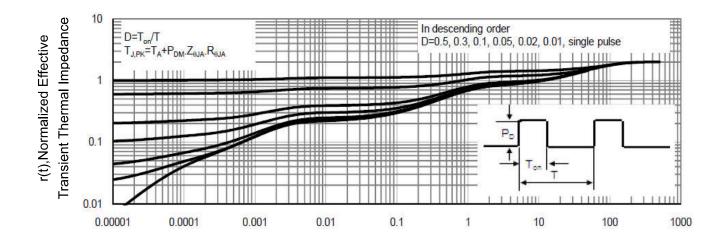
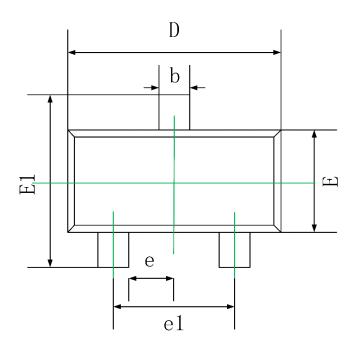


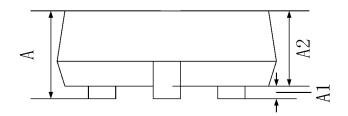
Figure 11 Normalized Maximum Transient Thermal Impedance

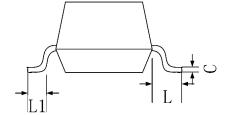
Square Wave Pluse Duration(sec)



SOT-23 Package Information







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055

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TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7

NTE2384 NTE2969 NTE6400A DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6 C3M0021120D DMN13M9UCA6-7

BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IRF40SC240ARMA1 IPS60R1K0PFD7SAKMA1

IPS60R360PFD7SAKMA1 IPS60R600PFD7SAKMA1